

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Bu-Seop JUNG</td> <td>02/26/2013</td> </tr> </tbody> </table>		Name	Execution Date	Bu-Seop JUNG	02/26/2013				
Name	Execution Date								
Bu-Seop JUNG	02/26/2013								
RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>Samsung Electronics Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>129 Samsung-ro, Yeongtong-gu, Suwon-si</td> </tr> <tr> <td>City:</td> <td>Gyeonggi-do</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> </table>		Name:	Samsung Electronics Co., Ltd.	Street Address:	129 Samsung-ro, Yeongtong-gu, Suwon-si	City:	Gyeonggi-do	State/Country:	KOREA, REPUBLIC OF
Name:	Samsung Electronics Co., Ltd.								
Street Address:	129 Samsung-ro, Yeongtong-gu, Suwon-si								
City:	Gyeonggi-do								
State/Country:	KOREA, REPUBLIC OF								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13778874</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13778874				
Property Type	Number								
Application Number:	13778874								
CORRESPONDENCE DATA									
<p>Fax Number: 2012269246  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>          Phone: 201-226-9245          Email: jeryl.bizzoco@chareiter.com          Correspondent Name: Cha &amp; Reiter, LLC          Address Line 1: 17 Arcadian Avenue          Address Line 2: Suite 208          Address Line 4: Paramus, NEW JERSEY 07652</p>									
ATTORNEY DOCKET NUMBER:	4500-1-194								
NAME OF SUBMITTER:	Steve Cha								
<p>Total Attachments: 2          source=4500-1-194_Assignment#page1.tif          source=4500-1-194_Assignment#page2.tif</p>									

CH \$40.00 13778874

**Assignment of Invention and Patent Application**

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration,

1) Bu-Seop JUNG of #910-704, 27, Bongyeong-ro, 1517beong-gil, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea

(hereinafter **Assignor**) hereby sells, assigns, transfers, and sets over unto:

**SAMSUNG ELECTRONICS CO., LTD.** of  
**129 SAMSUNG-RO, YEONGTONG-GU, SUWON-SI, GYEONGGI-DO, 443-742**  
**REPUBLIC OF KOREA**

(hereinafter **Assignee**) the entire right, title and interest for the United States Of America as defined in 35 U.S.C. Section 261, in and to the invention entitled as:

**METHOD AND APPARATUS FOR MANAGING A GROUP PROFILE IN A WI-FI DIRECT COMMUNICATION SYSTEM**

invented by **Assignor**; the application for United States patent therefor, invented by **Assignor**; any patent or reissues of any patent that may be granted thereon; and any applications which are continuations, continuation-in-part, substitutes, or divisions of said application. **Assignor** authorizes **Assignee** to enter the date of signature and/or Serial Number and Filing Date in the above. **Assignor** also authorizes and requests the Commissioner of Patents and Trademarks to issue any resulting patent(s) to the said **Assignee**, for its interests as **Assignee**, its successors, assigns and legal representatives. The undersigned agrees that the attorney of record in said application shall hereafter act on behalf of said **Assignee**; and **Assignor** further conveys to **Assignee** all priority rights resulting from the above-identified application for United States Patent. **Assignor** agrees to execute all papers, give any required testimony and perform other lawful acts, as deemed essential by **Assignee** to perfect **Assignee's** interest in any resulting patent of the United States, and to acquire, hold, enforce, convey, and uphold the validity of said patent and reissues and extensions thereof, and **Assignee's** interest therein.

**SIGNED ON THE DATES(S) INDICATED BESIDE MY/OUR SIGNATURE(S):**

**Name of First Inventor: Bu-Seop JUNG**

Bu-Seop JUNG  
Signature of inventor

Dated: 26-02-2013

WITNESSED: Paek